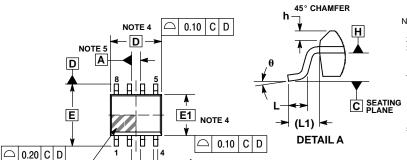
PIN ONE LOCATION

В

TOP VIEW



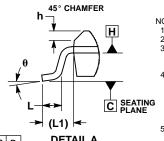
DATE 19 MAY 2017

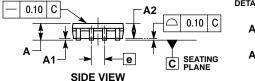


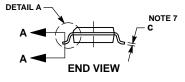
⊕ 0.25 C A-B D

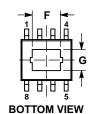
8x b

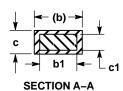
NOTES 3



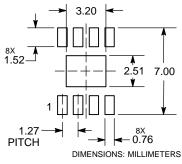








RECOMMENDED SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- 1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS
 DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.004mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRU-SIONS, OR GATE BURRS, MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006mm PER SIDE.
 DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR
 PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.010mm PER SIDE. 5. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.

DIM MIN MAX A 1.35 1.75 A1 0.10 A2 1.35 1.65 b 0.31 0.51 b1 0.28 0.48 c 0.17 0.25 c1 0.17 0.23 D 4.90 BSC E 6.00 BSC e 1.27 BSC e 1.27 BSC F 2.24 3.20 G 1.55 2.51 h 0.25 0.50 L 0.40 1.27 L1 1.04 REF θ 0.0 8°		MILLIMETERS		
A1 0.10 A2 1.35 1.65 b 0.31 0.51 b1 0.28 0.48 c 0.17 0.25 c1 0.17 0.23 D 4.90 BSC E 6.00 BSC E1 3.90 BSC e 1.27 BSC F 2.24 3.20 G 1.55 2.51 h 0.25 0.50 L 0.40 1.27 L1 1.04 REF	DIM	MIN	MAX	
A2 1.35 1.65 b 0.31 0.51 b1 0.28 0.48 c 0.17 0.25 c1 0.17 0.23 D 4.90 BSC E 6.00 BSC E1 3.90 BSC e 1.27 BSC F 2.24 3.20 G 1.55 2.51 h 0.25 0.50 L 0.40 1.27 L1 1.04 REF	Α	1.35	1.75	
b 0.31 0.51 b1 0.28 0.48 c 0.17 0.25 c1 0.17 0.23 D 4.90 BSC E 6.00 BSC e 1.27 BSC F 2.24 3.20 G 1.55 2.51 h 0.25 0.50 L 0.40 1.27 L1 1.04 REF	A1		0.10	
b1 0.28 0.48 c 0.17 0.25 c1 0.17 0.23 D 4.90 BSC E1 3.90 BSC e 1.27 BSC F 2.24 3.20 G 1.55 2.51 h 0.25 0.50 L 0.40 1.27 L1 1.04 REF	A2	1.35	1.65	
c 0.17 0.25 c1 0.17 0.23 D 4.90 BSC E 6.00 BSC E1 3.90 BSC e 1.27 BSC F 2.24 3.20 G 1.55 2.51 h 0.25 0.50 L 0.40 1.27 L1 1.04 REF	b	0.31	0.51	
c1 0.17 0.23 D 4.90 BSC E 6.00 BSC E1 3.90 BSC e 1.27 BSC F 2.24 3.20 G 1.55 2.51 h 0.25 0.50 L 0.40 1.27 L1 1.04 REF	b1	0.28	0.48	
D 4.90 BSC E 6.00 BSC E1 3.90 BSC e 1.27 BSC F 2.24 3.20 G 1.55 2.51 h 0.25 0.50 L 0.40 1.27 L1 1.04 REF	С	0.17	0.25	
E 6.00 BSC E1 3.90 BSC e 1.27 BSC F 2.24 3.20 G 1.55 2.51 h 0.25 0.50 L 0.40 1.27 L1 1.04 REF	с1	0.17	0.23	
E1 3.90 BSC e 1.27 BSC F 2.24 3.20 G 1.55 2.51 h 0.25 0.50 L 0.40 1.27 L1 1.04 REF	D	4.90 BSC		
e 1.27 BSC F 2.24 3.20 G 1.55 2.51 h 0.25 0.50 L 0.40 1.27 L1 1.04 REF	Е	6.00	BSC	
F 2.24 3.20 G 1.55 2.51 h 0.25 0.50 L 0.40 1.27 L1 1.04 REF	E1	3.90	BSC	
G 1.55 2.51 h 0.25 0.50 L 0.40 1.27 L1 1.04 REF	е	1.27 BSC		
h 0.25 0.50 L 0.40 1.27 L1 1.04 REF	F	2.24	3.20	
L 0.40 1.27 L1 1.04 REF	G	1.55	2.51	
L1 1.04 REF	h	0.25	0.50	
	L	0.40	1.27	
θ 0° 8°	L1			
	θ	0 °	8 °	

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code

Α = Assembly Location

= Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present and may be in either location. Some products may not follow the Generic Marking.

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PAGE 2 OF 2

ISSUE	REVISION	DATE
0	RELEASED FOR PRODUCTION. REQ. BY E. MULANAPHY	16 DEC 2003
Α	ADDED FOOTPRINT AND UPDATED MARKING. REQ. BY K. VALDEZ	25 JAN 2005
В	ADDED PIN 1 BAR AND DOT INDICATORS TO MARKING DIAGRAM. REQ. BY S. MOHAMMED	09 JUN 2005
С	MODIFIED EXPOSED PAD DIMENSIONS OF THE SOLDER FOOTPRINT. REQ. BY B. MARQUIS.	19 MAY 2017

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